



10/17
P. Walker
2-24-03

PATENT

Customer No. 22,852

Attorney Docket No. 04329.2622

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
)
Gaku MINAMIHABA, et al.) Group Art Unit: 2823
)
Serial No.: 09/932,943) Examiner: Lee, Hsien Ming
)
Filed: August 21, 2001)
)
For: SLURRY FOR CHEMICAL)
MECHANICAL POLISHING AND)
METHOD OF MANUFACTURING)
SEMICONDUCTOR DEVICE)

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

AMENDMENT

In reply to the Office Action dated November 8, 2002, with a period for response extending through February 10, 2003 (February 8th being a Saturday), Applicants amend the application as follows, and respectfully request the Examiner's reconsideration in view of the following remarks:

IN THE ABSTRACT:

Please replace the current abstract with the Abstract attached on a separate page. The full text of the Abstract in clean form is as follows:

A method of manufacturing a semiconductor device uses a slurry for chemical mechanical polishing during the manufacturing process, the slurry containing polishing particles comprising colloidal particles whose primary particles have a diameter ranging from 5 to 30 nm,

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